LASER X

Semi-auto Eutectic Die Bonder

Product Features

- Placement accuracy of ± 1.5 μ m (3 σ)
- Ability to handle tiny chips
- Apply LD and Submount cocrystal welding

Performance Parameter

Description		Parameter
Chip	Application	COC
	Chip size	0.15mm⩽Chip size⩽1.5mm
	Substrate size	0.15mm⩽Substrate size⩽4mm
Velocity	Production cycle（1 chip)	70s
Accuracy	Patch pressure	10g~100g
	XY Placement accuracy	+/-1.5um@3sigma (chip<1mm)
	Die rotation accuracy	0.3deg@3sigma
Camera	Sensor resolution ratio	3072x2048
	FOV	1.8x1.2(4x lens)
Eutectic System	Maximum temperature	450℃ （Minimum heating time 1.5s)
	Heating method	Pulse heating
	Heating speed/Cooling speed	⩽100°/Sec
	Temperature accuracy	+/-5°
	Shielding Gas	Nitrogen
Electrical specification	Power Supply	220VAC/50Hz
	Energy Consumption	3.5kVA
Dimensions and Weight	Air	4 ~ 6Kgf/cm2
	Dimensions	500(L)x500(W)x800 mm(H)
	Weight	100kg

LASER X
LASER X Technology(Shenzhen) Co., Ltd.

Address： Yufengda Industrial Park,
Guangming District, Shenzhen City,
Guangdong Province, China

Sales Hot Line：18923755822
E-mail: laserx.xs@laserx.net
Website：www.laserx.net/en